

### Description

The  $\mu$ PD4363B is a 16,384-word by 4-bit static RAM fabricated with advanced silicon-gate technology. A unique design using CMOS peripheral circuits and N-channel memory cells with polysilicon resistors makes the  $\mu$ PD4363B a high-speed device that requires very low power and no clock or refreshing.

The  $\mu$ PD4363B is packaged in a standard 300-mil, 24-pin plastic DIP and 24-pin plastic SOJ.

### **Features**

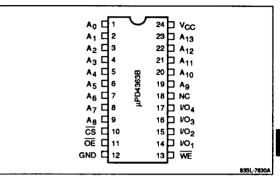
- □ Single + 5-volt power supply
- Fully static operation—no clock or refreshing
- □ TTL-compatible inputs and outputs
- □ Common I/O capability
- □ OE eliminates the need for external bus buffers
- □ Three-state outputs
- Low power dissipation
  - 130 mA max (active)
  - -2 mA max (standby)
- Standard 300-mil, 24-pin plastic DIP and 24-pin plastic SOJ packaging

### Ordering Information

Part Number	Access Time (max)	Package		
μPD4363BCR-12	12 ns	24-pin plastic DIP		
CR-15	15 ns	•		
CR-20	20 ns	-		
μPD4363BLA-12	12 ns	24-pin plastic SO		
LA-15	15 ns	_		
LA-20	20 ns	•		

### Pin Configuration

#### 24-Pin Plastic DIP or SOJ



### Pin Identification

Address inputs
Data inputs and outputs
Chip select
Output enable
Write enable
Ground
+5-volt power supply
No connection



**Absolute Maximum Ratings** 

Supply voltage, V <sub>CC</sub>	- 0.5 to + 7.0 V
Input and output voltages, V <sub>IN</sub> (Note 1)	-0.5 to V <sub>CC</sub> + 0.5 V
Operating temperature, T <sub>OPR</sub>	0 to +70°C
Storage temperature, T <sub>STG</sub>	- 55 to + 125°C
Power dissipation, PD	1.0 W

Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

#### Notes:

(1)  $V_{\text{IN}}$  (min) = -3.0 V for 10 ns pulse.

### Capacitance

 $T_A = 25^{\circ}C$ ; f = 1 MHz;  $V_{IN}$  and  $V_{OUT} = 0$  V (Note 1)

Parameter	Symbol	Min	Тур	Max	Unit
Input capacitance	CIN			6	pF
Output capacitance	C <sub>DOUT</sub>			8	pF

#### Notes:

(1) This parameter is sampled and not 100% tested.

## **Recommended Operating Conditions**

Parameter	Symbol	Min	Тур	Max	Unit	
Supply voltage	Vcc	4.5	5.0	5.5	٧	
Input voltage, high	VIH	2.2		V <sub>CC</sub> + 0.3	٧	
Input voltage, low	V <sub>IL</sub>	- 0.5		0.8	٧	
Operating temperature	TA	0		70	°C	

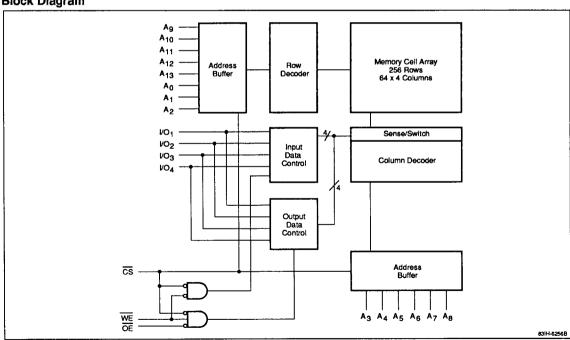
#### Notes:

(2)  $V_{IL} = -3.0 \text{ V}$  for 10 ns pulse.

### **Truth Table**

Function	CS	WE	ŎĔ	Input/Output	lcc
Not selected	Н	Х	Х	High-Z	Standby
Read	L	Н	L	D <sub>OUT</sub>	Active
D <sub>OUT</sub> disabled	L	Н	Н	High-Z	Active
Write	L	L	X	D <sub>IN</sub>	Active

**Block Diagram** 





#### **DC Characteristics**

 $T_A = 0 \text{ to } +70^{\circ}\text{C}; V_{CC} = +5.0 \text{ V } \pm 10\%$ 

Symbol	Min	Тур	Max	Unit	Test Conditions
ILI	-2		2	μΑ	V <sub>IN</sub> = 0 V to V <sub>CC</sub> ; V <sub>CC</sub> = max
lιο	-2		2	μΑ	V <sub>OUT</sub> = 0 V to V <sub>CC</sub> ; $\overline{\text{CS}}$ or $\overline{\text{OE}}$ = V <sub>IH</sub> ; V <sub>CC</sub> = max
Isa			20	mA	CS = VIH
l <sub>SB1</sub>			2	mA	$\overline{\text{CS}} = V_{\text{CC}} - 0.2 \text{V}; V_{\text{IN}} \le 0.2 \text{V or} \ge V_{\text{CC}} - 0.2 \text{V}$
VoL			0.4	٧	l <sub>OL</sub> = 8.0 mA
V <sub>он</sub>	2.4			V	I <sub>OH</sub> = -4.0 mA
	I <sub>LI</sub> I <sub>LO</sub> I <sub>SB</sub> I <sub>SB1</sub> V <sub>OL</sub>	L1		I <sub>L1</sub>	I <sub>L1</sub> -2     2     μA       I <sub>LO</sub> -2     2     μA       I <sub>SB</sub> 20     mA       I <sub>SB1</sub> 2     mA       V <sub>OL</sub> 0.4     V

## **AC Characteristics**

 $T_A = 0 \text{ to } +70^{\circ}\text{C}; V_{CC} = +5.0 \text{ V } \pm 10\%$ 

Parameter	Symbol	μPD4363B-12		μPD4363B-15		μPD4363B-20			
		Min	Max	Min	Max	Min	Max	Unit	Test Conditions
Read Operation									
Operating supply current	lcc		130		120		110	mΑ	CS = V <sub>IL</sub> ; I <sub>DOUT</sub> = 0 mA
Read cycle time	tRC	12		15		20		ns	(Note 2)
Address access time	t <sub>AA</sub>		12		15	-	20	ns	
Chip select access time	tacs		12		15		20	ns	
Output hold from address change	tон	2		3		3		ns	
Chip select to output in low-Z	t <sub>LZ</sub>	2		3		3		ns	(Note 3)
Chip deselect to output in high-Z	tHZ	0	7	0	7	0	8	ns	(Note 4)
Output enable access time	†0E		8		9		10	ns	
Output enable to output in low-Z	toLZ	0		0		0		ns	(Note 3)
Output disable to output in high-Z	tонz	0	7	0	7	0	8	ns	(Note 4)
Chip select to power-up time	t <sub>PU</sub>	0		0		0		ns	
Chip deselect to power-down time	t <sub>PD</sub>	0	7	0	10	0	12	ns	
Write Operation									
Write cycle time	twc	12	···	15		20		ns	(Note 2)
Chip select to end of write	tcw	11		13		15		ns	
Address valid to end of write	t <sub>AW</sub>	11		13		15		ns	
Address setup time	tas	0		0		0		ns	
Write pulse width	t <sub>WP</sub>	10		12		14		ns	
Write recovery time	twR	1		1		1		ns	
Data valid to end of write	t <sub>DW</sub>	7		7		8		ns	
Data hold time	t <sub>DH</sub>	0		0		0		ns	-
Write enable to output in high-Z	twz	0	7	0	7	0	8	ns	(Note 4)
Output active from end of write	tow	0	<del></del>	0		0		ns	(Note 3)

#### Notes:

- Input pulse levels = GND to 3.0 V; input pulse rise and fall times = 5 ns; timing reference levels = 1.5 V; see figures 1 and 2 for output load.
- (2) All read and write cycle timings are referenced from the last valid address to the first transitioning address.
- (3) Transition is measured at ±200 mV from steady-state voltage with the loading shown in figure 2.
- (4) Transition is measured at  $V_{OL}$  + 200 mV and  $V_{OH}$  200 mV with the loading shown in figure 2.



Figure 1. Output Load

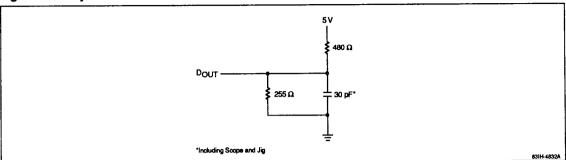
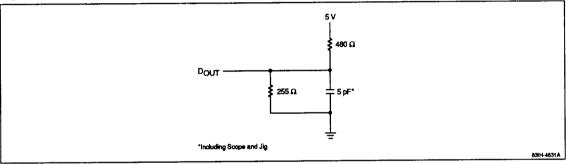


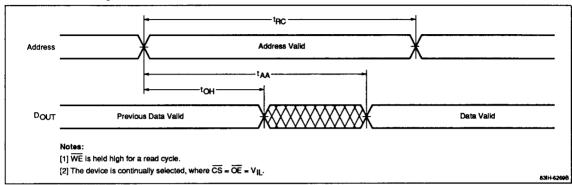
Figure 2. Output Load for  $t_{HZ}$ ,  $t_{LZ}$ ,  $t_{OHZ}$ ,  $t_{OLZ}$ ,  $t_{WZ}$ , and  $t_{OW}$ 



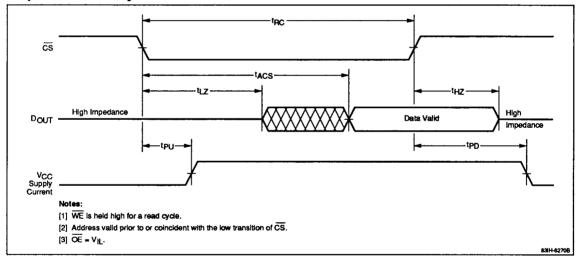


# **Timing Waveforms (cont)**

### Address Access Cycle



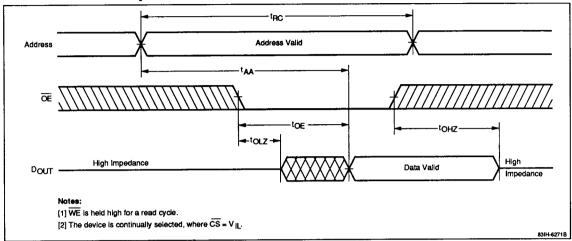
# Chip Select Access Cycle



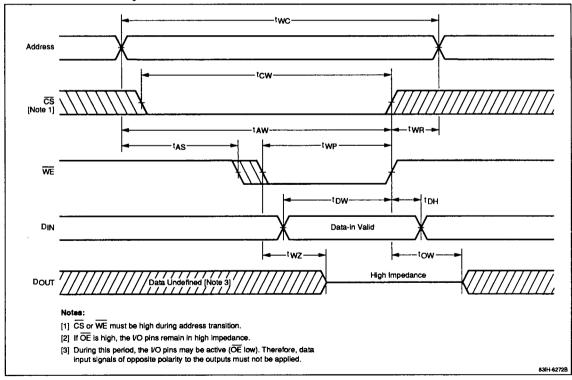


# **Timing Waveforms (cont)**

## **OE-Controlled Access Cycle**



### WE-Controlled Write Cycle





## **Timing Waveforms (cont)**

# **CS-Controlled Write Cycle**

